

IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~striketrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please AMEND claims 1, 2 and 5 and ADD new claims 10 and 11 in accordance with the following:

1. (Currently Amended) A multilayer wiring board comprising:
a core portion including a core insulating layer containing a carbon fiber material;
a first lamination wiring portion bonded to the core portion and having a laminated structure including at least a first insulating layer and a first wiring pattern, the first insulating layer containing glass cloth; and
a second lamination wiring portion bonded to the first lamination wiring portion and having a laminated structure including at least a second insulating layer and a second wiring pattern;
wherein the core portion, the first lamination wiring portion and the second lamination wiring portion are arranged in a stack; and
wherein the core insulating layer, the first insulating layer and the second insulating layer have respective thermal expansion coefficients defined in a surface-spreading direction transverse to a stacking direction of these three layers, the thermal expansion coefficient of the core insulating layer being smallest among said three layers, the thermal expansion coefficient of the second insulating layer being largest among said three layers, the thermal expansion coefficient of the first insulating layer being larger than that of the core layer but smaller than that of the second insulating layer.

2. (Currently Amended) A multilayer wiring board comprising:
a core portion including a core insulating layer containing a carbon fiber material;
two first lamination wiring portions respectively bonded to opposite sides of the core portion, each of the first lamination wiring portions having a laminated structure including at least a first insulating layer and a first wiring pattern, the first insulating layer containing glass cloth; and
a second lamination wiring portion bonded to one of the first lamination wiring portions

and having a laminated structure including at least a second insulating layer and a second wiring pattern;

wherein the core portion, the first lamination wiring portions and the second lamination wiring portion are arranged in a stack; and

wherein the core insulating layer, the first insulating layer and the second insulating layer have respective thermal expansion coefficients defined in a surface-spreading direction transverse to a stacking direction of these three layers, the thermal expansion coefficient of the core insulating layer being smallest among said three layers, the thermal expansion coefficient of the second insulating layer being largest among said three layers, the thermal expansion coefficient of the first insulating layer being larger than that of the core layer but smaller than that of the second insulating layer.

3. (Original) The multilayer wiring board according to Claim 2, further comprising an additional second lamination wiring portion, wherein the additional second lamination wiring portion has a laminated structure including at least a second insulating layer and a second wiring pattern, and is bonded to the first lamination wiring portion other than said one of the first lamination wiring portions.

4. (Original) The multilayer wiring board according to Claim 1, further comprising a through-hole via extending through both the core portion and the first lamination wiring portion, wherein the through-hole via is insulated from the core portion by an insulating layer surrounding the through-hole via.

5. (Currently Amended) The multilayer wiring board according to Claim 1, wherein ~~the core insulating layer, the first insulating layer and the second insulating layer have respective thermal expansion coefficients defined in a surface-spreading direction transverse to a stacking direction of these three layers,~~ the thermal expansion coefficient of the core insulating layer ~~being~~ is no smaller than -3 ppm/K but smaller than 8 ppm/K below 150°C , the thermal expansion coefficient of the first insulating layer being no smaller than 8 ppm/K but smaller than 20 ppm/K below 150°C , the thermal expansion coefficient of the second insulating layer being no smaller than 20 ppm/K but smaller than 100 ppm/K below 150°C .

6. (Original) The multilayer wiring board according to Claim 1, wherein the carbon fiber material is provided in a form of mesh, cloth or nonwoven fabric.

7. (Original) The multilayer wiring board according to Claim 1, wherein the core insulating layer contains the carbon fiber material at a rate of 30 through 80 vol%.

8. (Original) The multilayer wiring board according to Claim 1, wherein the carbon fiber material is graphitized at a rate not smaller than 99%.

9. (Original) The multilayer wiring board according to Claim 1, wherein the core insulating layer is formed of a material containing a resin that is selected from a group consisting of: polysulfone, polyethersulfone, polyphenylsulfone, polyphthalamide, polyamideimide, polyketone, polyacetal, polyimide, polycarbonate, modified-polyphenyleneether, polyphenyleneoxide, polybutyreneterephthalate, polyacrylate, polyphenylenesulfide, polyetheretherketone, tetrafluoroethylene, epoxy, cyanateester, and bismaleimide.

10. (New) A multilayer wiring board comprising:
a stack, said stack comprising:
a core portion including a core insulating layer containing a carbon fiber material;
a first lamination wiring portion bonded to the core portion and having a laminated structure including at least a first insulating layer and a first wiring pattern, the first insulating layer containing glass cloth; and
a second lamination wiring portion bonded to the first lamination wiring portion and having a laminated structure including at least a second insulating layer and a second wiring pattern.

11. (New) The multilayer wiring board according to Claim 10, comprising further:
an opposite first lamination wiring portion bonded to a side of the core portion opposite the first lamination wiring portion and having an opposite laminated structure including at least an opposite first insulating layer and an opposite first wiring pattern, the opposite first insulating layer containing said glass cloth.